

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yung-Yao Lee</td> <td>02/26/2013</td> </tr> <tr> <td>Ying-Ying Wang</td> <td>02/27/2013</td> </tr> </tbody> </table>		Name	Execution Date	Yung-Yao Lee	02/26/2013	Ying-Ying Wang	02/27/2013
Name	Execution Date						
Yung-Yao Lee	02/26/2013						
Ying-Ying Wang	02/27/2013						
RECEIVING PARTY DATA							
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City:	Hsin-Chu						
State/Country:	TAIWAN						
Postal Code:	300-77						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13778386</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13778386		
Property Type	Number						
Application Number:	13778386						
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ATTORNEY DOCKET NUMBER:	TSMCP259US						
NAME OF SUBMITTER:	Thomas G. Eschweiler						
Total Attachments: 4 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif							

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TSMC Docket No. TSMC2012-1393

U.S. Patent Appln. No.

Docket No. TSMCP259US

Filing Date:

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

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AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled "**OVERLAY SAMPLING METHODOLOGY**" for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

was filed on _____ and accorded U.S. Serial No. _____; or

will be filed without this executed PATENT ASSIGNMENT. ASSIGNOR hereby authorizes and requests ASSIGNEE'S legal representatives, the attorneys

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associated with Customer No. _____, to insert below in this document this APPLICATION's U.S. Serial Number and filing date, when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for

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Filing Date:

United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

02,26,2013

Date

Yung-Yao, Lee

Name 1st Inventor Yung-Yao Lee

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Filing Date:

2.27.2013
Date

Ying-Ying Wang
Name 1st Inventor Ying-Ying Wang